

ABSTRACT OF THE DISCLOSURE

In a laser beam machining method for a wiring board, a
5 machined portion of the wiring board is irradiated with a
pulsed laser beam for a beam irradiation time ranging from
about 10 to about 200 μ s and with energy density of about 20
J/cm² or more, thereby machining the wiring board, for
example, drilling for a through-hole and a blind via hole,
10 grooving, and cutting for an outside shape.

DOCUMENT 245660